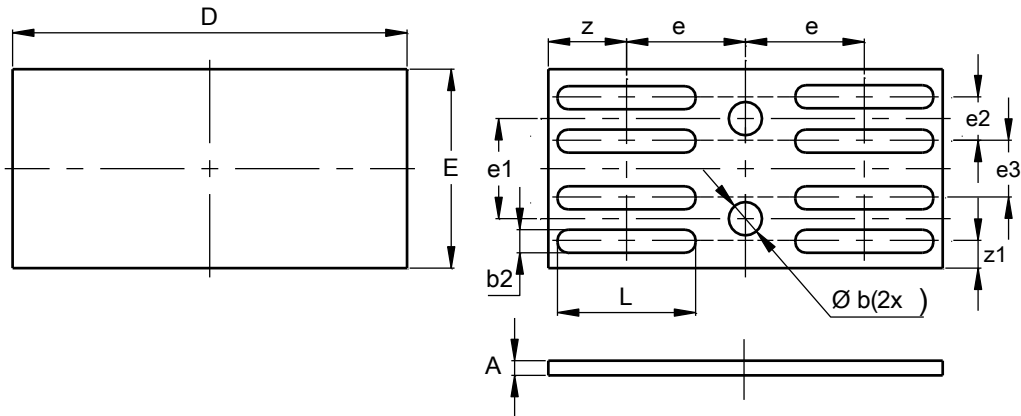


Package Outline Dimensions

X4-DSN3015-10

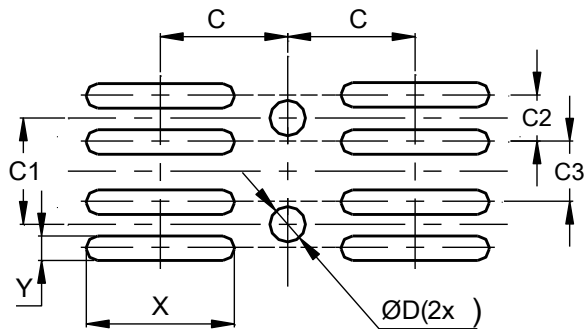


X4-DSN3015-10			
Dim	Min	Max	Typ
A	0.09	0.16	0.11
b	--	--	0.25
b2	--	--	0.175
D	2.93	3.03	2.98
E	1.44	1.54	1.49
e	--	--	0.895
e1	--	--	0.75
e2	--	--	0.325
e3	--	--	0.425
L	--	--	1.04
z	--	--	0.595
z1	--	--	0.2075

All Dimensions in mm

Suggested Pad Layout

X4-DSN3015-10



Dimensions	Value (in mm)
C	0.895
C1	0.750
C2	0.325
C3	0.425
D	0.25
X	1.04
Y	0.175

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.